**PATENT ASSIGNMENT**

Electronic Version v1.1  
Stylesheet Version v1.1

**SUBMISSION TYPE:** NEW ASSIGNMENT  
**NATURE OF CONVEYANCE:** ASSIGNMENT

**CONVEYING PARTY DATA**

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
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<tbody>
<tr>
<td>Fu-Yung Tsai</td>
<td>04/13/2012</td>
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**RECEIVING PARTY DATA**

<table>
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<tr>
<th>Name:</th>
<th>ADVANCED SEMICONDUCTOR ENGINEERING, INC.</th>
</tr>
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<tbody>
<tr>
<td>Street Address:</td>
<td>No. 26, Chin 3rd Road</td>
</tr>
<tr>
<td>Internal Address:</td>
<td>Nantze Export Processing Zone</td>
</tr>
<tr>
<td>City:</td>
<td>Kaohsiung</td>
</tr>
<tr>
<td>State/Country:</td>
<td>TAIWAN</td>
</tr>
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**PROPERTY NUMBERS Total: 1**

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<th>Property Type</th>
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<tr>
<td>Application Number</td>
<td>13448059</td>
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**CORRESPONDENCE DATA**

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*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.*  
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Address Line 2: SUITE 725  
Address Line 4: IRVINE, CALIFORNIA 92612

**ATTORNEY DOCKET NUMBER:** ASE2544

**NAME OF SUBMITTER:** Howard J. Klein

Total Attachments: 1  
source=ASE2544--Assgn Signed#page 1.tif
ASSIGNMENT OF APPLICATION

WHEREAS, I, Fu-Yung Tsai, of No. 4, Caizhuang Ln., Xizhou Township, Changhua County 524, Taiwan R.O.C. and a citizen of Taiwan R.O.C. ("Assignor"), have an interest in the invention entitled "SEMICONDUCTOR PACKAGES WITH HEAT DISSIPATION STRUCTURES AND RELATED METHODS" which is the subject of a United States application for patent entitled above; and

WHEREAS, Advanced Semiconductor Engineering, Inc., a corporation organized and existing under and by virtue of the laws of Taiwan R.O.C. with an address at No. 26, Chin 3rd Road, Nantze Export Processing Zone, Kaohsiung, Taiwan R.O.C. ("Assignee"), is desirous of acquiring Assignor's interest in the invention;

NOW THEREFORE, Assignor acknowledges receipt and adequacy of good and valuable consideration in exchange for this Assignment, and assigns to Assignee and its successors in interest, the full and exclusive right, title and interest to the invention described in the patent application listed above, in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, for the full term of the patent, including extensions of time, the same as if held by Assignor had this Assignment not been made.

Assignor covenants and agrees to cooperate with Assignee and execute all instruments or documents requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to the following: non-provisional utility, provisional, continuation, continuation-in-part, divisional, renewal or substitute, reissue, re-examination, or extension.

Assignor covenants and agrees to cooperate with Assignee in any litigation regarding the invention, patents or applications regarding the invention, including testifying for the benefit of Assignee.

Assignor covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Signed and Accepted by:

\[ \text{Fu-Yung Tsai} \]

\[ 2\text{/12/13} \]

Date

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